



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE4274D V33		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA001132296						
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		379.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.945	0.78	0.78	7760	7760
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		170	
	non noble metal	iron	7439-89-6	0.215	0.06		567	
	non noble metal	copper	7440-50-8	215.017	56.65	56.73	566492	567229
	non noble metal	aluminium	7429-90-5	0.123	0.03	0.03	323	323
wire	non noble metal	aluminium	7429-90-5	0.123	0.03	0.03	323	323
encapsulation	organic material	carbon black	1333-86-4	0.267	0.07		704	
	plastics	epoxy resin	-	12.285	3.24		32366	
	inorganic material	silicondioxide	60676-86-0	120.979	31.87	35.18	318737	351807
leadfinish	non noble metal	tin	7440-31-5	3.740	0.99	0.99	9854	9854
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	239	240
solder	non noble metal	tin	7440-31-5	0.093	0.02		244	
	noble metal	silver	7440-22-4	0.116	0.03		305	
	non noble metal	lead	7439-92-1	4.420	1.16	1.21	11646	12195
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.05	5.06	50526	50592
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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